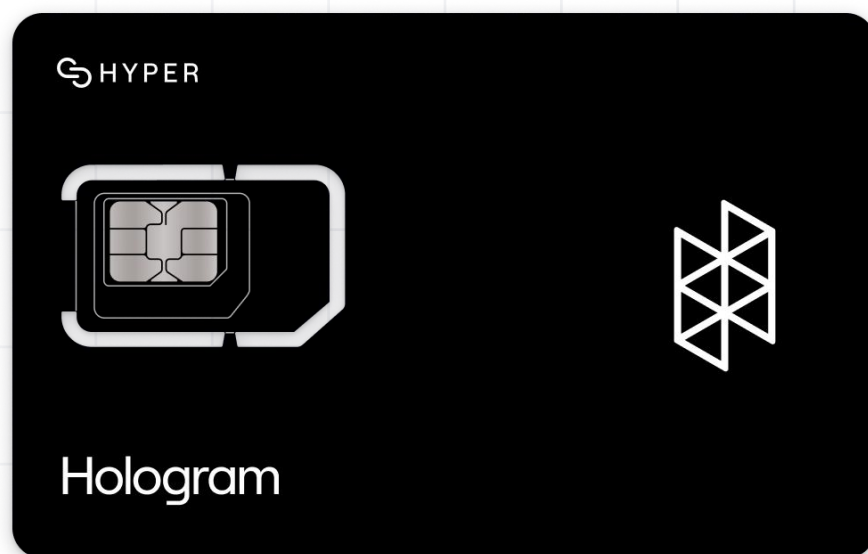


# Triple cut format



# Hyper eUICC SIM

# Hyper eUICC SIM – Triple cut format

## Product overview

A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIM platform is eUICC compliant and remotely updates coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

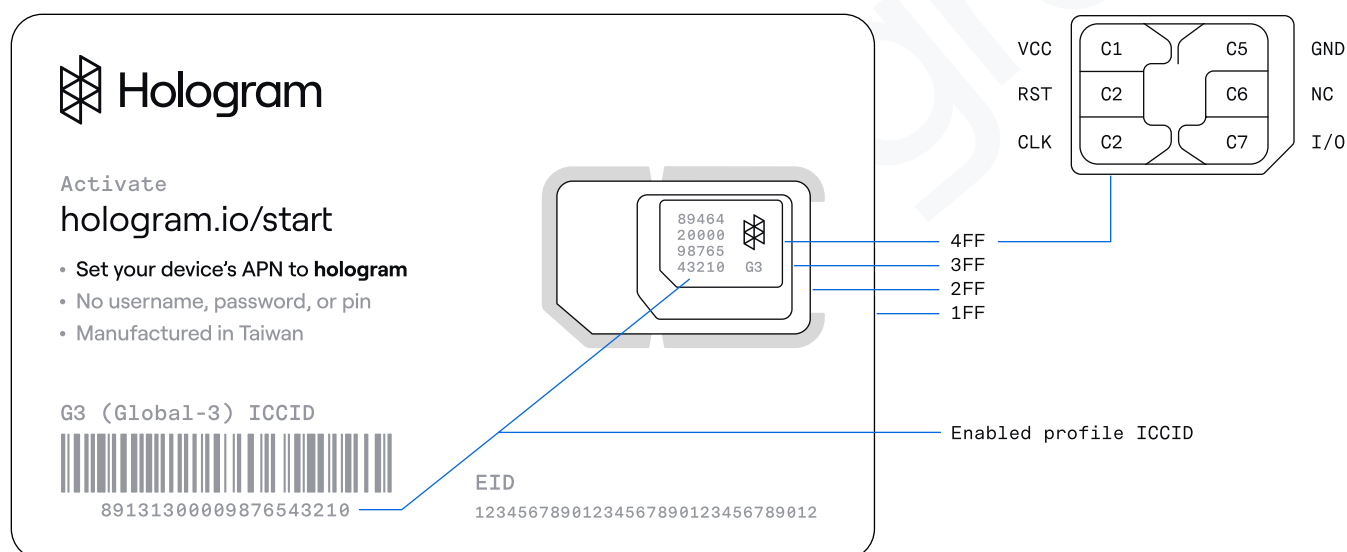
## Primary part number

G3-F

## Network availability

Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

## Card layout



## Physical characteristics

### Size

|     |           |                      |
|-----|-----------|----------------------|
| 1FF | Full-size | 85.6 x 54 x 0.71 mm  |
| 2FF | Mini-SIM  | 25 x 15 x 0.71 mm    |
| 3FF | Micro-SIM | 15 x 12 x 0.71 mm    |
| 4FF | Nano-SIM  | 12.3 x 8.8 x 0.71 mm |

### Pin definitions

|    |     |               |
|----|-----|---------------|
| C1 | VCC | Input Voltage |
| C2 | RST | Reset         |
| C3 | CLK | Clock         |
| C5 | GND | Ground        |
| C6 | NC  | No Connect    |
| C7 | I/O | Input/Output  |

# Hardware features

## Chip type

|           |              |
|-----------|--------------|
| Supplier  | Infineon     |
| Chip Code | SLM17ECB800B |

## Electrical

|                   |               |
|-------------------|---------------|
| Operating Voltage | 1.62V to 5.5V |
|-------------------|---------------|

## Hardware characteristics

|                         |                 |
|-------------------------|-----------------|
| Grade                   | Industrial      |
| Operational Temperature | −40°C to +105°C |
| Data Retention          | 20 years @ 25°C |
| Write Endurance         | >1.5M cycles    |
| Memory (NVM)            | 800 KB          |
| Memory (SRAM)           | 20 KB           |

## AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 – Smart Cards; UICC–Terminal interface; Physical and logical characteristics  
ISO/IEC 7816, T=0 standard for Cards with contacts – USB electrical interface and operating procedures

# Compliance

|                                      |                                                                                                                         |                                                                                                                                                                                                                                           |
|--------------------------------------|-------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Chip                                 |  Common Criteria                       | EAL 4+ PP-0084 (chipset)<br>Certificate: BSI-DSZ-CC-1126-V2-2021                                                                                                                                                                          |
|                                      |                                      | SGP.01 Embedded SIM Remote Provisioning Architecture v4.2<br>SGP.02 Embedded UICC Technical Specification v4.2<br>SGP.16 M2M Compliance Process v1.3                                                                                      |
| OS                                   |  TRUSTED<br>CONNECTIVITY<br>ALLIANCE | eUICC Profile Package Interoperable Format Technical Specification v2.3.1                                                                                                                                                                 |
|                                      |                                      | Card Specification Version 2.3.1<br>Card Specification Amendments A, B, D & E                                                                                                                                                             |
| Software                             |                                      | Java Card 3 Platform, Classic Edition version 3.0.5                                                                                                                                                                                       |
|                                      |                                      | Release 16                                                                                                                                                                                                                                |
| Remote SIM provisioning              |                                      | SGP.01 Embedded SIM Remote Provisioning Architecture v4.2<br>SGP.02 Embedded UICC Technical Specification v4.2<br>SGP.16 M2M Compliance Process v1.3                                                                                      |
| Supplier's Declaration of Conformity |                                                                                                                         | Manufactured according to the following standards: <ul style="list-style-type: none"><li>• RoHS 2015/863/EU</li><li>• Reach certification</li><li>• GSMA SAS-UP</li><li>• ISO 9001:2015</li><li>• ISO 27001</li><li>• ISO 14001</li></ul> |

# SIM features

## Profiles and fallback

|                       |                                 |
|-----------------------|---------------------------------|
| Available user memory | 414,384 B                       |
| Maximum profiles      | 10                              |
| Applet version        | v1 Fallback applet              |
| Default fallback mode | Return to previous, no recovery |

## Part numbers

| Active part numbers | Past part numbers |
|---------------------|-------------------|
| G3-F                | G3                |
| G3-G2-F             | —                 |
| G3-US2M-F           | —                 |
| G2-F                | GL2-AFB           |
| G1-F                | —                 |
| G1-G2-F             | —                 |
| US2+-G2-F           | GL2-AFB-USA2+     |
| US2M-G2-F           | GL2-AFB-USAM      |
| CA1-G2-F            | GL2-AFB-CA1       |
| G3-F-2FF            | —                 |

| Multipack labeling | Part numbers |
|--------------------|--------------|
| Single SIM         | G3-G2-F      |
| 100-pack           | G3-G2-F-100  |
| 1000-pack          | G3-G2-F-1000 |

## Multi-core card layout

